

2 Amp. Glass Passivated Bridge Rectifier

<p>Dimensions in mm.</p> <p>Plastic Case</p>	<p>Voltage 50 to 1000 V.</p> <p>Current 2 A.</p>
<p>• Mounting Instructions</p> <ul style="list-style-type: none"> • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. 	<ul style="list-style-type: none"> • Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • The plastic material carries U/L recognition 94 V-O.

Maximum Ratings, according to IEC publication No. 134

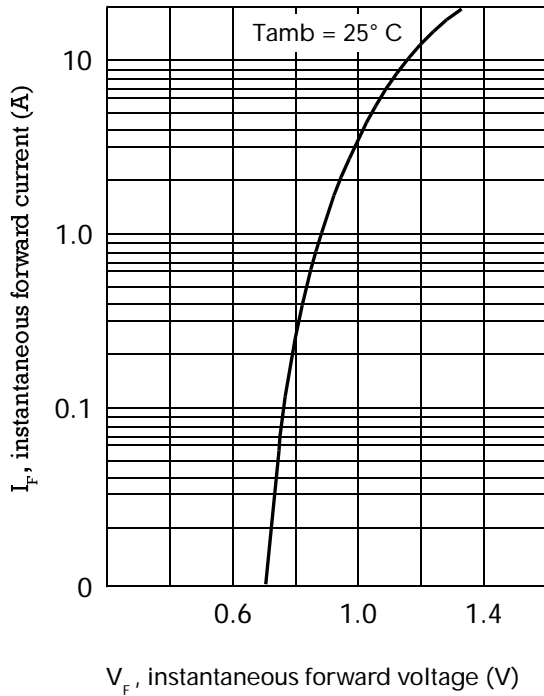
	FBI2A 4S1	FBI2B 4S1	FBI2D 4S1	FBI2G 4S1	FBI2J 4S1	FBI2K 4S1	FBI2M 4S1
V_{RRM}	Peak recurrent reverse voltage (V)						
V_{RMS}	Maximum RMS voltage (V)						
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink						
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)						
I^2t	Rating for fusing ($t < 8.3$ ms.)						
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)						
T_j	Operating temperature range						
T_{stg}	Storage temperature range						

Electrical Characteristics at $T_{amb} = 25^\circ\text{C}$

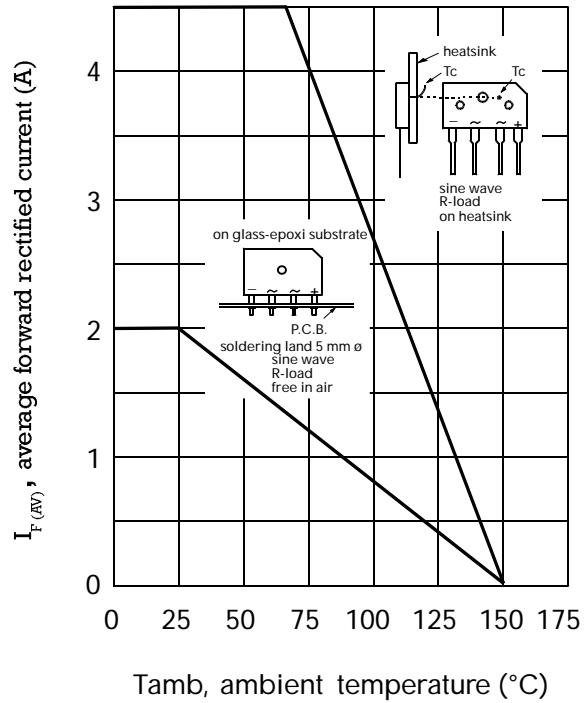
V_F	Max. forward voltage drop per element at $I_F = 2$ A	1.0 V
I_R	Max. reverse current per element at V_{RRM}	$5\mu\text{A}$
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	12°C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	40°C/W

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

